

[ABSTRACT]

A dicing/die bonding sheet (101) including: a pressure-sensitive adhesive layer (12) on a base material (11); and a film adhesive (13) on the pressure-sensitive adhesive layer (12), wherein the pressure-sensitive adhesive layer (12) has a thickness of 20 μm to 50 μm , and an elongation at break of the pressure-sensitive adhesive layer (12) is from 5 to 50%.

A method for producing a semiconductor chip (9) wherein: an intermediate structure is formed by providing a first surface (13a) of the film adhesive (13) of the dicing/die bonding sheet (101) with a semiconductor wafer; and the semiconductor wafer is divided by forming a notch (10) reaching the pressure-sensitive adhesive layer (12) from the surface of the semiconductor wafer but not reaching the base material (11) in the intermediate structure using a dicing blade.